

MODULE CARD AND IT'S MANUFACTURING METHOD

5 ABSTRACT OF THE DISCLOSURE

A manufacturing method of a module card comprises steps of: providing a base board having a golden finger; mounting a chip on the base board for electrically connecting to the golden finger; and forming a packing layer on the chip for forming the module card. A module card 10 comprises: a base board; a chip mounting on a surface of the base board; a golden finger on the board and electrically connecting to the chip; and a packing layer forming on the chip for covering the chip.

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